



- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

- : TO-220AC
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- : Tin plated leads, solderable per J-STD-002 and JESD22-B102
- : As marked

■ (T_a=25 Unless otherwise specified)

Device marking code			MBR10300
Repetitive Peak Reverse Voltage	VRRM	V	300
Average Rectified Output Current @60Hz sine wave, R-load, T _a =25	I _O	A	10
Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, T _a =25	IFSM	A	200
Current Squared Time @1ms≤t<8.3ms T _j =25	I ² t	A ² s	167
Storage Temperature	T _{stg}		-55 ~ +150



■ Ta=25 Unless otherwise specified				
Thermal Resistance	Between junction and case	RθJ-C	W	2.0

■ (Example)					
MBR10300	Approximate 1.8				



